

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) A device comprising:

a semiconductor substrate;

a pixel cell array integrated with the semiconductor substrate;

a liquid crystal layer in contact with the pixel cell array;

a substantially transparent protective cover coupled to the liquid crystal layer; ~~and~~

a base coupled to the semiconductor substrate,

wherein thermal expansion characteristics of the base are substantially similar to thermal expansion characteristics of the protective cover, and

a chip carrier having an upper surface coupled to a lower surface of the base.

2. (cancelled)

3. (original) A device according to Claim 1, wherein the protective cover is composed of a first material of a first thickness, and the base is composed substantially of the first material of substantially the first thickness.

4. (cancelled)

5. (currently amended) A device according to Claim 4, comprising:
a semiconductor substrate;
a pixel cell array integrated with the semiconductor substrate;
a liquid crystal layer in contact with the pixel cell array;
a substantially transparent protective cover coupled to the liquid crystal layer;
a base coupled to the semiconductor substrate,
wherein thermal expansion characteristics of the base are substantially similar to thermal expansion characteristics of the protective cover; and
a chip carrier coupled to the base, the chip carrier defining a recess, the base mounted within the recess.
6. (previously presented) A device according to Claim 5, a foot of the recess having a first thickness, the first thickness substantially smaller than a thickness of the semiconductor substrate, the pixel cell array, the liquid crystal layer, the cover, and the base.
7. (withdrawn) A device according to Claim 5, the chip carrier defining an opening, wherein the protective cover extends partially into, fully into, partially through or fully through the opening.
8. (withdrawn) A device according to Claim 5, the chip carrier defining an opening, wherein the base extends partially into, fully into, partially through or fully through the opening.

9. (withdrawn) A device according to Claim 8, further comprising:

a heat sink coupled to the base.

10. (original) A device according to Claim 5, further comprising:

a heat sink coupled to the chip carrier.

11. (cancelled)

12. (cancelled)

13. (cancelled)

14. (cancelled)

15. (cancelled)

16. (withdrawn) A device comprising:

a microdisplay integrated circuit (IC);

a substantially transparent protective cover coupled to the microdisplay IC; and

a chip carrier defining an opening,

wherein the cover extends partially into, fully into, partially through or fully through the opening.

17. (withdrawn) A device according to Claim 16, further comprising:

a base coupled to the microdisplay IC.

18. (withdrawn) A device according to Claim 17, further comprising:

a heat sink coupled to the base.

19. (withdrawn) A device according to Claim 16, wherein the chip carrier is coupled to the microdisplay IC.

20. (withdrawn) A device according to Claim 19, wherein the microdisplay IC comprises imaging elements and a bonding surface, the bonding surface comprising first conductors to carry electrical signals to the imaging elements,

wherein the chip carrier comprises second conductors to carry the electrical signals, and

wherein the first conductors contact respective ones of the second conductors.

21. (withdrawn) A method comprising:

fabricating at least one set of imaging elements on an upper surface of a semiconductor substrate; and

affixing a base to a lower surface of the semiconductor substrate to generate substantially negligible mechanical stress between the semiconductor substrate and the base in a case that the imaging elements are operated within a range of operating temperatures.

22. (withdrawn) A method according to Claim 21, wherein affixing the base comprises:
- applying an epoxy to one or both of the base and the lower surface of the semiconductor substrate;
- bringing the base and the lower surface into contact with one another while at a temperature equal to at least one operating temperature of the imaging elements; and
- partially curing the epoxy at at least one operating temperature of the imaging elements.

23. (withdrawn) A method according to Claim 21, wherein thermal expansion characteristics of the base are substantially to thermal expansion characteristics of the semiconductor substrate.

24. (withdrawn) A method comprising:
- fabricating at least one set of imaging elements on an upper surface of a semiconductor substrate; and
- affixing a base to a lower surface of the semiconductor substrate to substantially flatten the semiconductor substrate.

25. (withdrawn) A method according to Claim 24, wherein affixing the base comprises:

affixing the base to the lower surface of the semiconductor substrate to substantially flatten the semiconductor substrate in a case that the imaging elements are operated within a range of operating temperatures.

26. (withdrawn) A method according to Claim 24, wherein affixing the base comprises:
- applying an epoxy to one or both of the base and the lower surface of the semiconductor substrate;
- bringing the base and the lower surface into contact with one another while at a temperature equal to at least one operating temperature of the imaging elements; and
- partially curing the epoxy at at least one operating temperature of the imaging elements.

27. (currently amended) A system comprising:
- an Ultra High Pressure light source to emit light;
- a condenser lens to condense the light;
- a display device to receive the condensed light and to emit image light, the display device comprising:
- a semiconductor substrate;
- a pixel cell array integrated with the semiconductor substrate;
- a liquid crystal layer in contact with the pixel cell array;
- a substantially transparent protective cover coupled to the liquid crystal layer; ~~and~~
- a base coupled to the semiconductor substrate, thermal expansion characteristics of the base being substantially similar to thermal expansion characteristics of the protective cover; and

a chip carrier having an upper surface coupled to a lower surface of the base; and
a projector lens to project the image light.

28. (currently amended) A system ~~according to Claim 27, comprising:~~
an Ultra High Pressure light source to emit light;
a condenser lens to condense the light;
a display device to receive the condensed light and to emit image light, the display device comprising:
a semiconductor substrate;
a pixel cell array integrated with the semiconductor substrate;
a liquid crystal layer in contact with the pixel cell array;
a substantially transparent protective cover coupled to the liquid crystal layer; and
a base coupled to the semiconductor substrate, thermal expansion characteristics of the base being substantially similar to thermal expansion characteristics of the protective cover; and
a projector lens to project the image light;
wherein the display device comprises:
a chip carrier,
wherein the chip carrier defines a recess, and
wherein the base is mounted within the recess.

29. (currently amended) A device ~~according to Claim 1, further comprising:~~

a semiconductor substrate;

a pixel cell array integrated with the semiconductor substrate;

a liquid crystal layer in contact with the pixel cell array;

a substantially transparent protective cover coupled to the liquid crystal layer;

a base coupled to the semiconductor substrate,

wherein thermal expansion characteristics of the base are substantially similar to thermal expansion characteristics of the protective cover; and

an electrode disposed between the liquid crystal layer and the protective cover,

wherein the protective cover is coupled to electrode.

30. (cancelled)